

3A, 200V - 1000V High Efficient Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I_F	3	A
V_{RRM}	200 - 1000	V
I_{FSM}	88	A
$T_{J\ MAX}$	150	°C
Package	DO-214AB (SMC)	
Configuration	Single die	



MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.250g (approximately)



DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	HS3D-K	HS3G-K	HS3J-K	HS3K-K	HS3M-K	UNIT
Marking code on the device		HS3D	HS3G	HS3J	HS3K	HS3M	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(\text{RMS})}$	140	280	420	560	700	V
Forward current	I_F	3				A	
Surge peak forward current single half sine-wave superimposed on rated load	$t = 8.3\text{ms}$	I_{FSM}	88				A
	$t = 1.0\text{ms}$		244				A
Junction temperature	T_J	-55 to +150				°C	
Storage temperature	T_{STG}	-55 to +150				°C	

THERMAL PERFORMANCE

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	25	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	54	°C/W
Junction-to-case thermal resistance	$R_{\Theta JC}$	18	°C/W

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ C$ unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
Forward voltage ⁽¹⁾	HS3D-K	$I_F = 1.5A, T_J = 25^\circ C$	V_F	0.81	-	V
		$I_F = 3.0A, T_J = 25^\circ C$		0.88	1.00	V
		$I_F = 1.5A, T_J = 125^\circ C$		0.66	-	V
		$I_F = 3.0A, T_J = 125^\circ C$		0.74	0.86	V
	HS3G-K	$I_F = 1.5A, T_J = 25^\circ C$		0.93	-	V
		$I_F = 3.0A, T_J = 25^\circ C$		1.06	1.30	V
		$I_F = 1.5A, T_J = 125^\circ C$		0.75	-	V
		$I_F = 3.0A, T_J = 125^\circ C$		0.87	1.08	V
	HS3J-K HS3K-K HS3M-K	$I_F = 1.5A, T_J = 25^\circ C$		1.33	-	V
		$I_F = 3.0A, T_J = 25^\circ C$		1.52	1.70	V
		$I_F = 1.5A, T_J = 125^\circ C$		0.98	-	V
		$I_F = 3.0A, T_J = 125^\circ C$		1.16	1.48	V
Reverse current @ rated V_R ⁽²⁾	$T_J = 25^\circ C$	I_R	-	10	μA	
			-	200	μA	
Reverse recovery time	HS3D-K HS3G-K	$I_F = 0.5A, I_R = 1.0A$ $I_{rr} = 0.25A$	t_{rr}	-	50	ns
	HS3J-K HS3K-K HS3M-K			-	75	ns
Junction capacitance	HS3D-K	1MHz, $V_R = 4.0V$	C_J	53	-	pF
	HS3G-K			37	-	pF
	HS3J-K HS3K-K HS3M-K			25	-	pF

Notes:

1. Pulse test with PW = 0.3ms
2. Pulse test with PW = 30ms

 ORDERING INFORMATION

ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
HS3x-K	DO-214AB (SMC)	3,000 / Tape & Reel

Notes:

1. "x" defines voltage from 200V(HS3D-K) to 1000V(HS3M-K)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

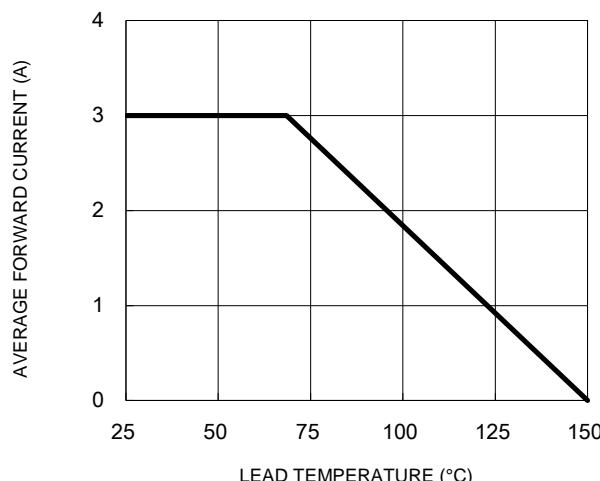


Fig.2 Typical Junction Capacitance

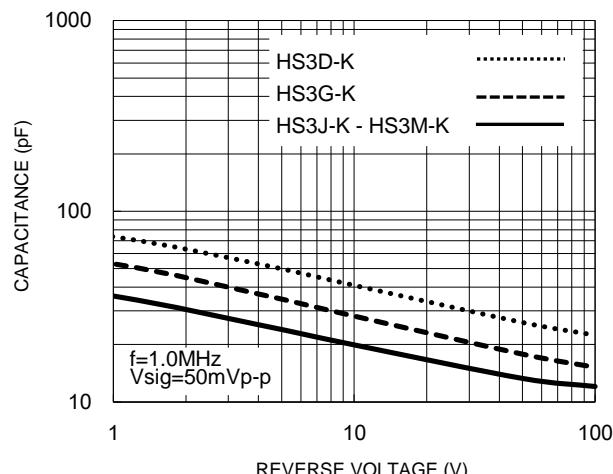


Fig.3 Typical Reverse Characteristics

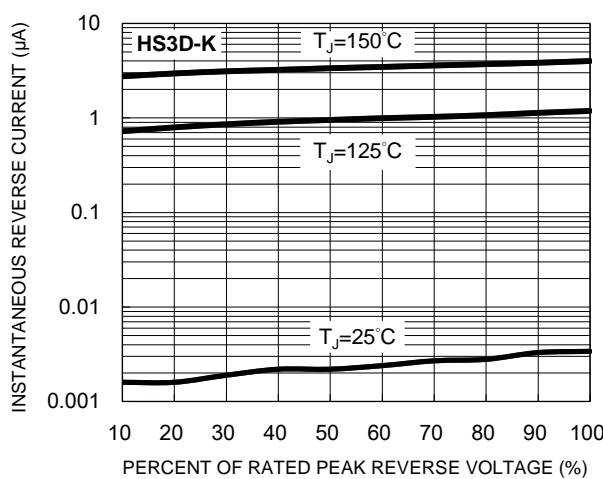


Fig.4 Typical Forward Characteristics

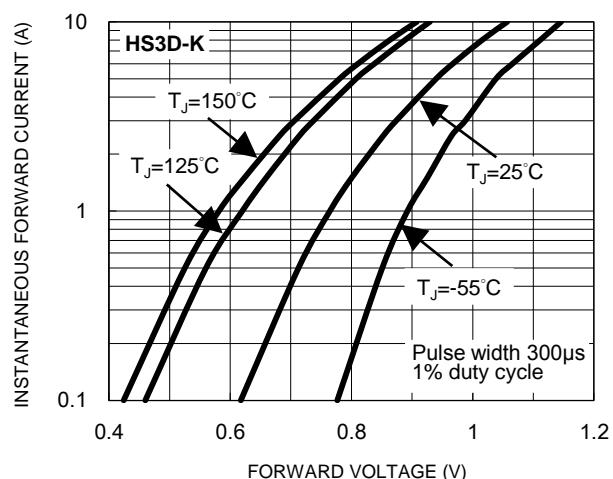


Fig.5 Typical Reverse Characteristics

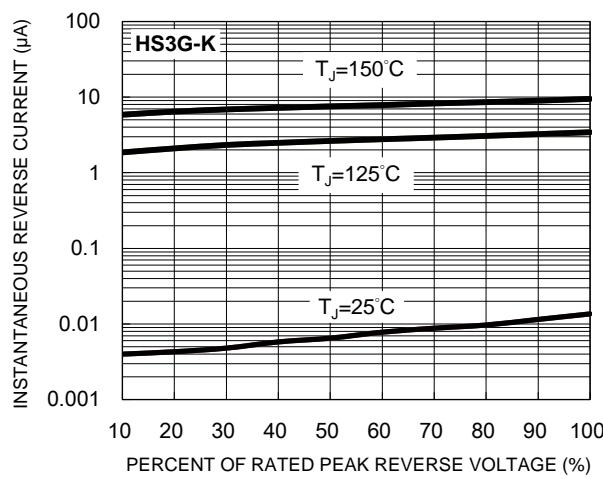
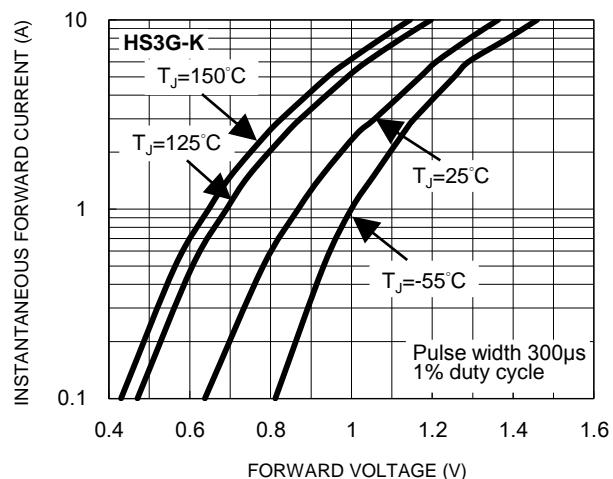


Fig.6 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.7 Typical Reverse Characteristics

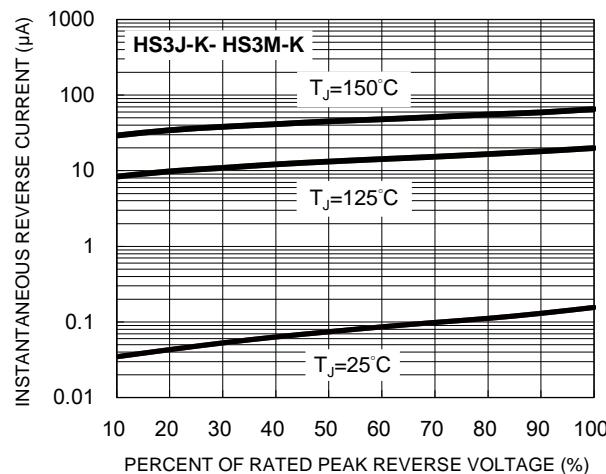


Fig.8 Typical Forward Characteristics

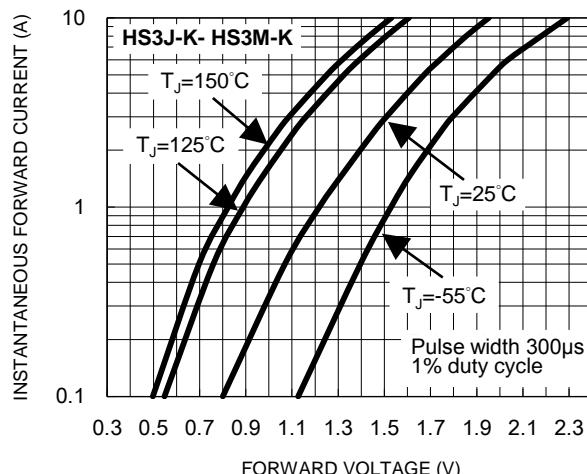
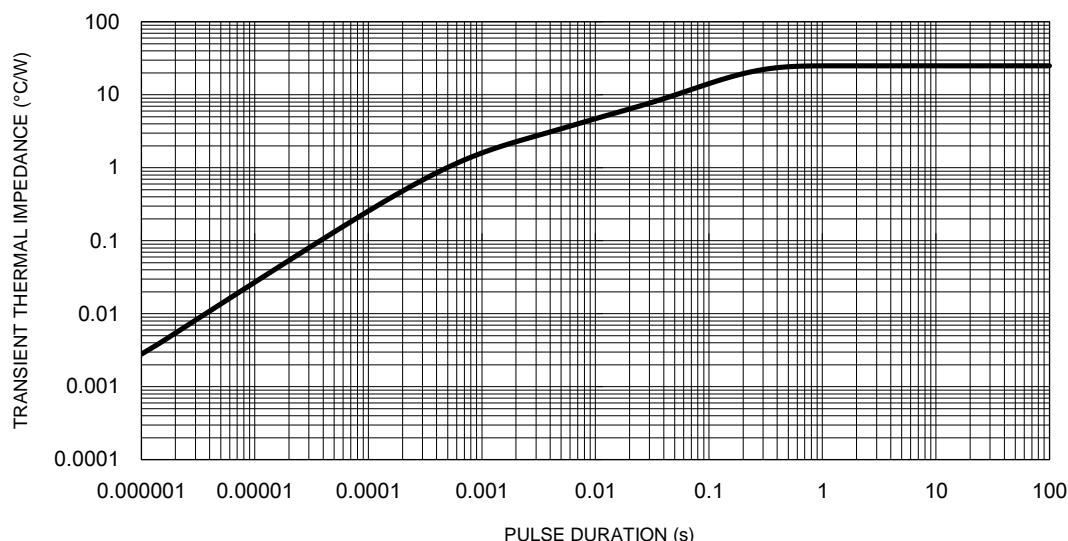
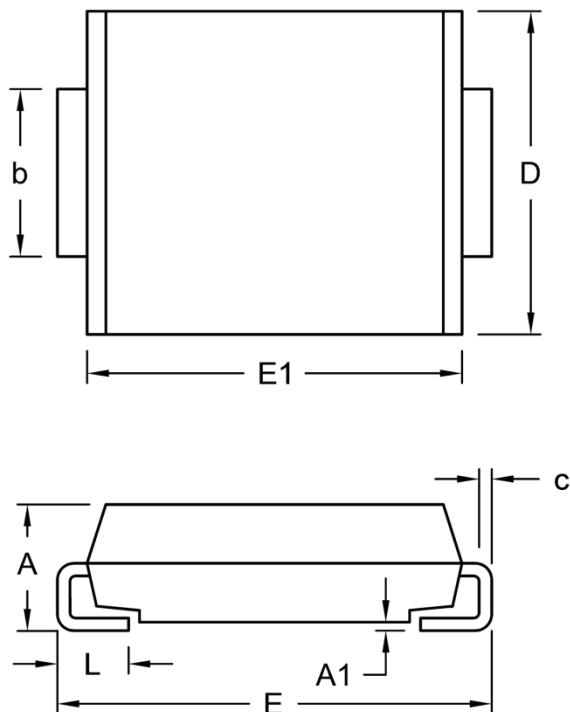
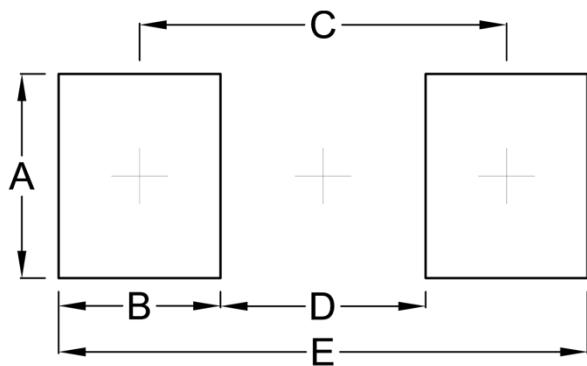


Fig.9 Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS
DO-214AB (SMC)


DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	1.99	2.61	0.078	0.103
A1	0.10	0.20	0.004	0.008
b	2.85	3.27	0.112	0.129
c	0.15	0.31	0.006	0.012
D	5.59	6.22	0.220	0.245
E	7.75	8.13	0.305	0.320
E1	6.60	7.11	0.260	0.280
L	0.76	1.52	0.030	0.060

SUGGESTED PAD LAYOUT


Symbol	Unit (mm)	Unit (inch)
A	3.82	0.150
B	3.03	0.119
C	6.87	0.270
D	3.84	0.151
E	9.90	0.390

MARKING DIAGRAM


P/N = Marking Code
 G = Green Compound
 YW = Date Code
 F = Factory Code

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